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(12) **United States Design Patent**
Wang

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(54) **WIRED OVER EAR HEADPHONE**

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(**) Term: **15 Years**

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(51) **LOC (13) Cl.** **14-01**

(52) **U.S. Cl.**
USPC **D14/205**

(58) **Field of Classification Search**
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CPC .. H04R 1/1083; H04R 1/1041; H04R 1/1016; H04R 5/0335; H02J 7/0044
See application file for complete search history.

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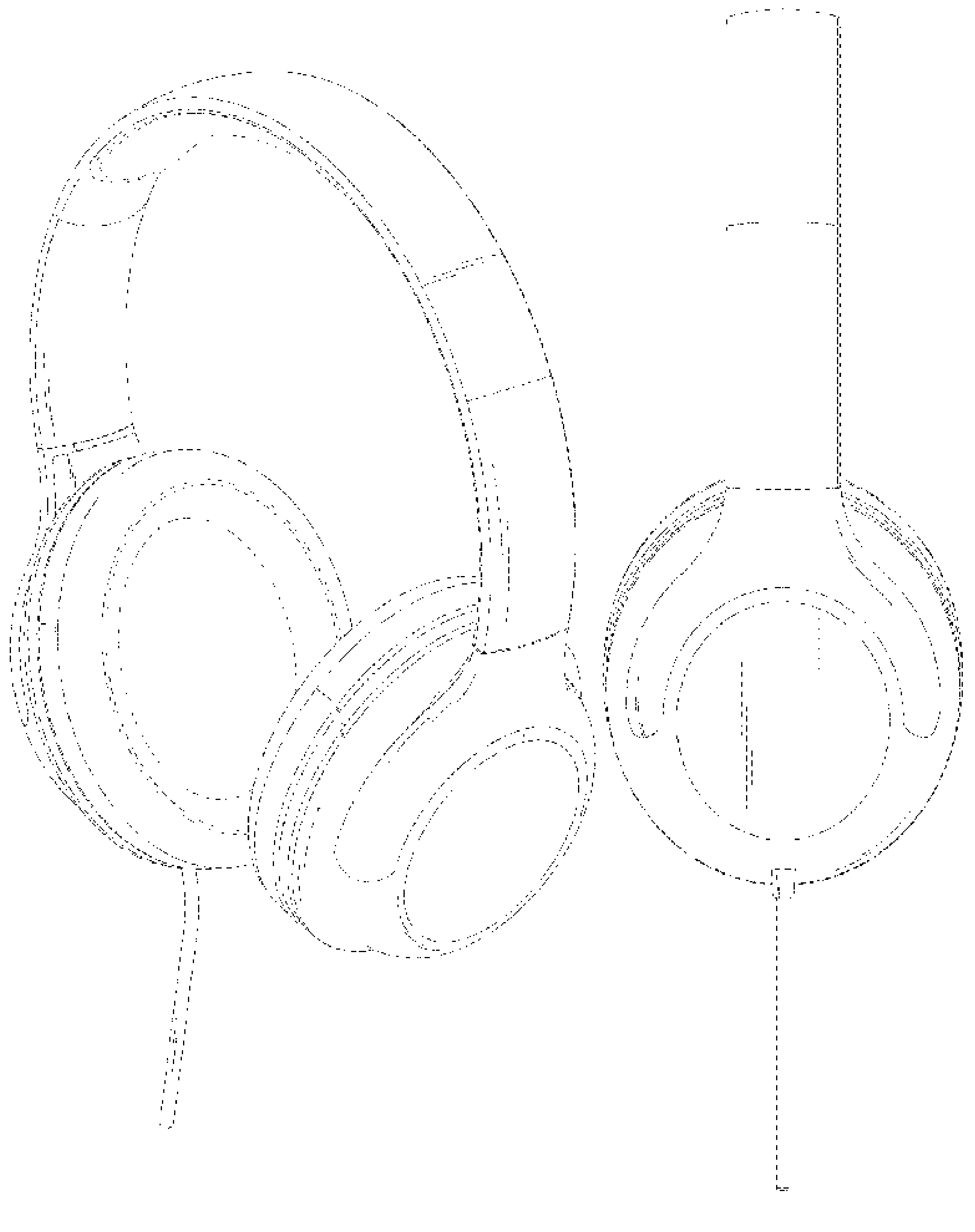
(57) **CLAIM**

The ornamental design for a wired over ear headphone, as shown and described.

DESCRIPTION

FIG **1** is a perspective view of a wired over ear headphone showing the claimed design;
FIG. **2** is a top plan view thereof;
FIG. **3** is a left side view thereof;
FIG. **4** is a front elevational view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a rear elevational view thereof; and,
FIG. **7** is a bottom plan view thereof.
The broken lines depict portions of the wired over ear headphone that form no part of the claimed design.

1 Claim, 7 Drawing Sheets



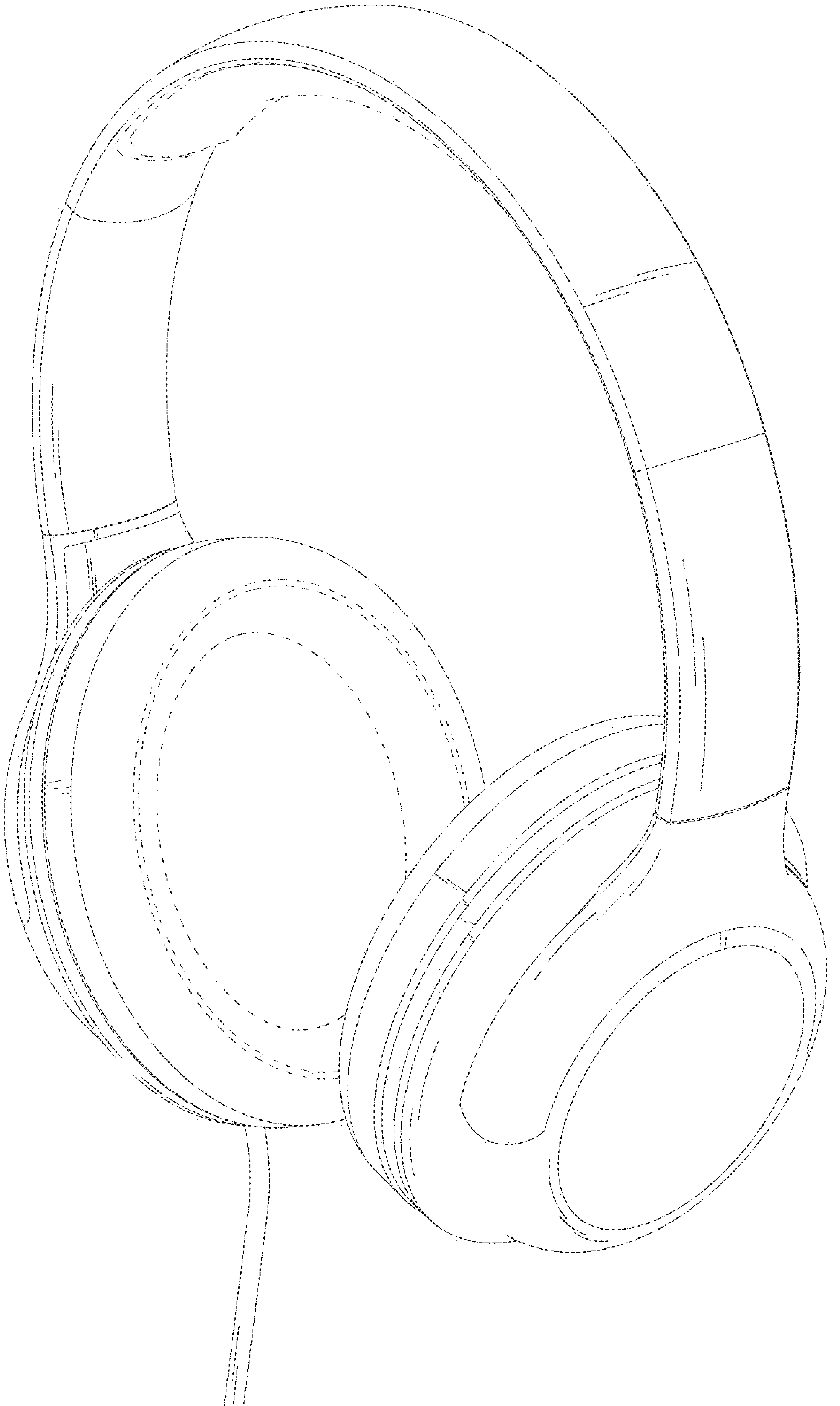


FIG.1

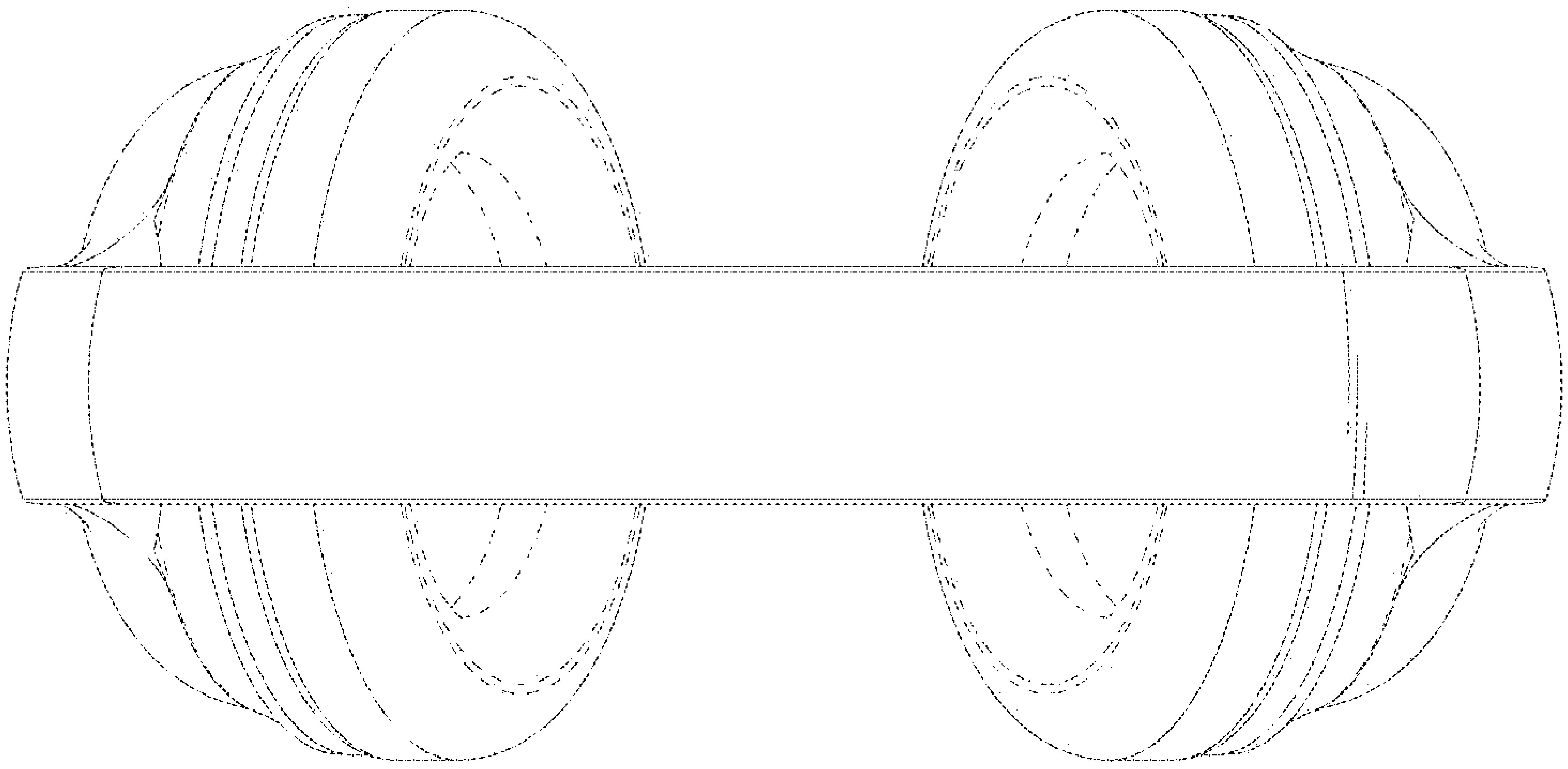


FIG.2

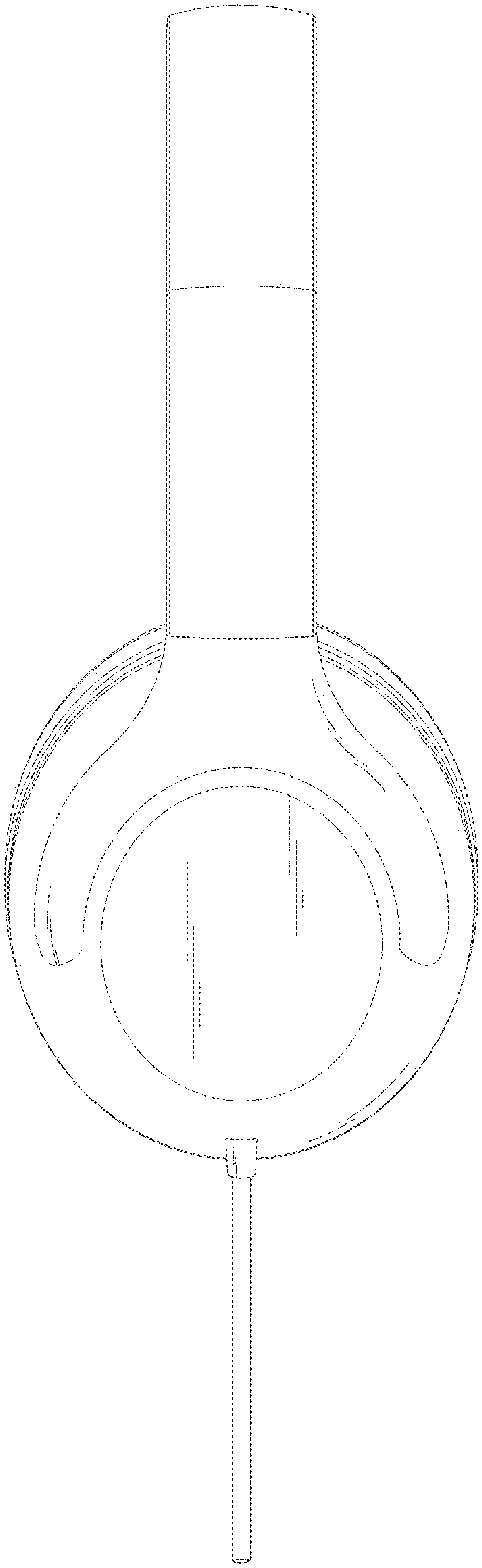


FIG.3

FIG. 4

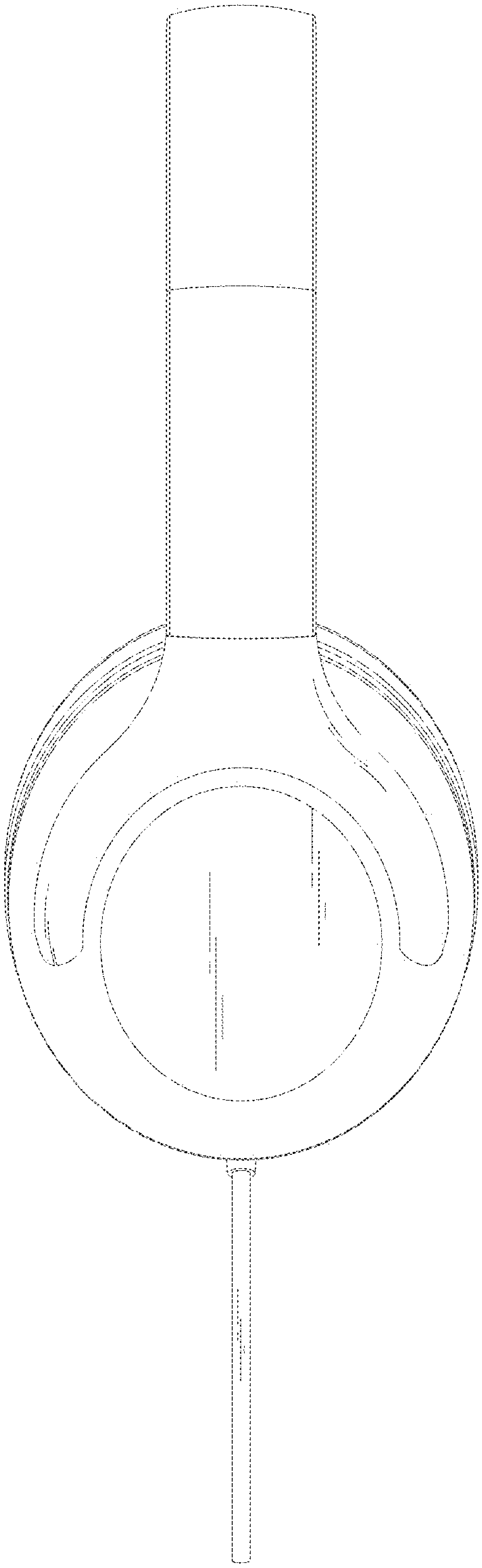


FIG.5

FIG. 6

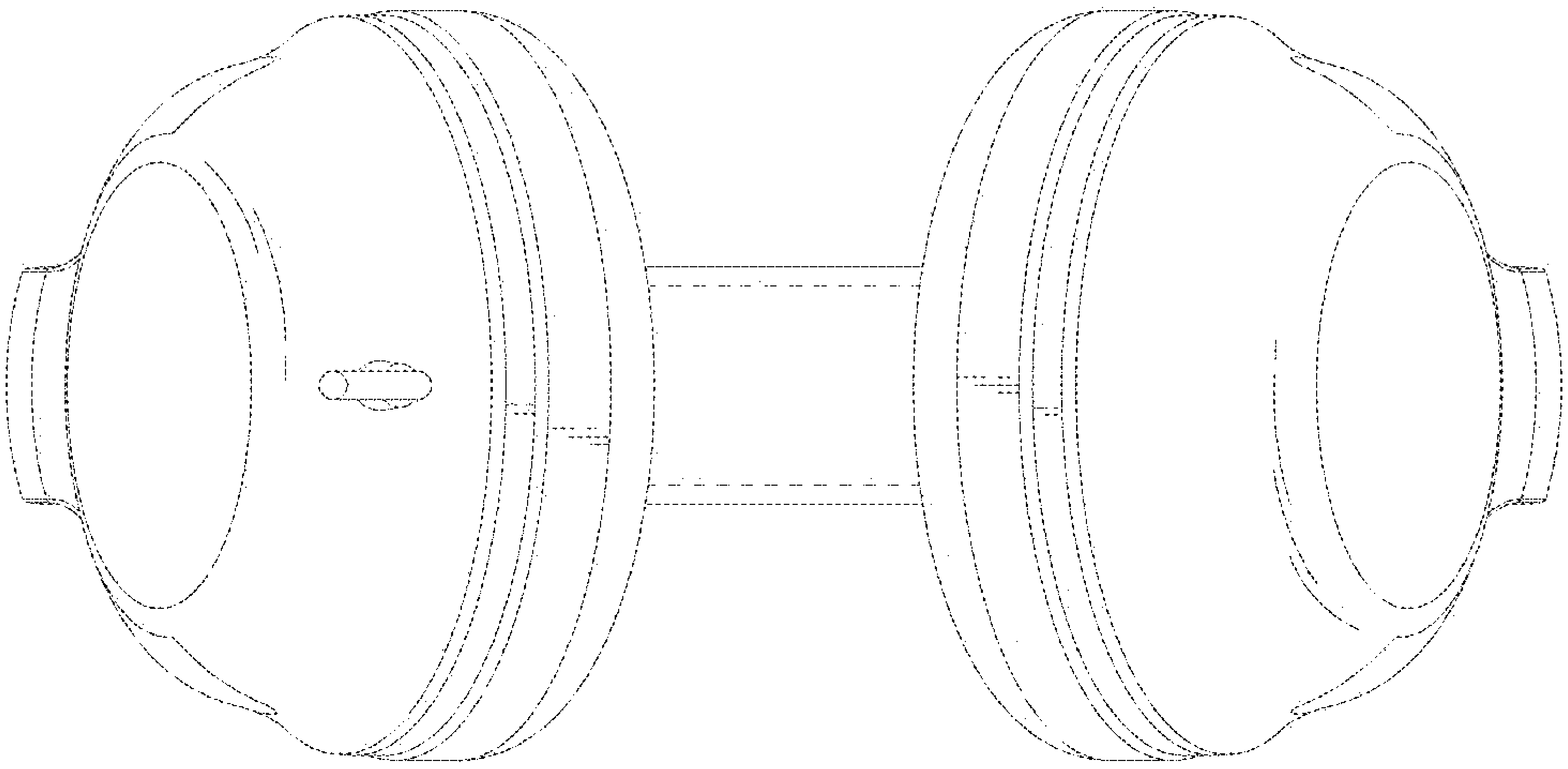


FIG.7